[TS04W1]

Nano/MEMS Processing & Packaging for Intelligent & Quantum Applications 1

Date & Time	July 8(Wed.), 2026 / 09:30-11:00
Place	Room 206B
Session Chair(s)	Prof. Hyeon-Ho Jeong (GIST)

TS04W1_I_1 ***Invited** 09:30-10:00

3D Integration of Nanoscale Photonics and Electronics for Future AI and Nano-Computing Systems

S. J. Ben Yoo
(University of California, Davis)

TS04W1_I_2 ***Invited** 10:00-10:30

MEMS-Based Integrated Photonic Elements for Ultra-Low-Power Programmability

Kyoungsik Yu
(Korea Advanced Institute of Science and Technology)

TS04W1_I_3 ***Invited** 10:30-11:00

Heterogeneous 3D Integration of III-V and Si CMOS for RF and Quantum Computing Applications

Jaeyong Jeong
(Ulsan National Institute of Science and Technology)